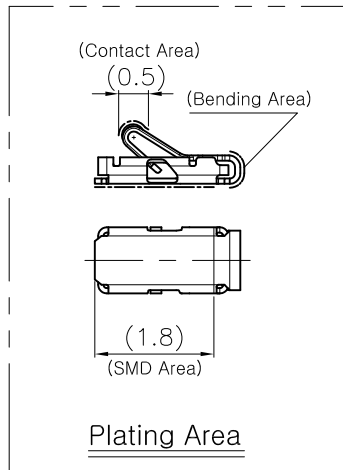
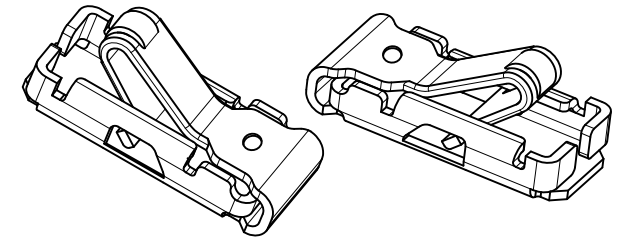
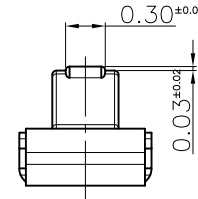
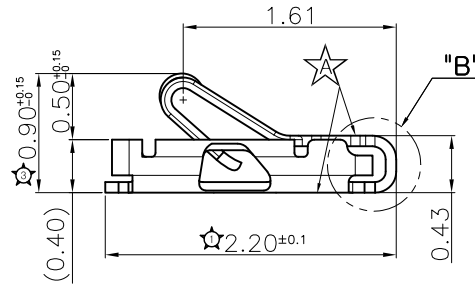
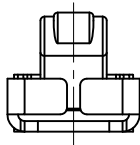
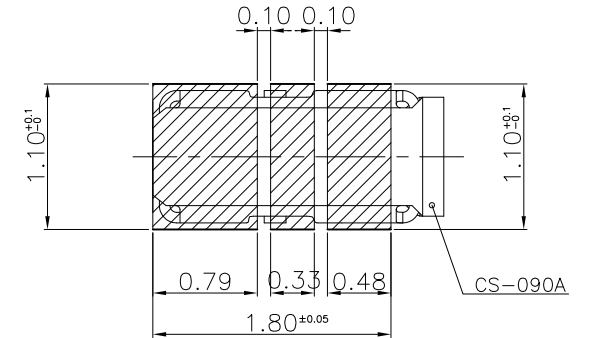
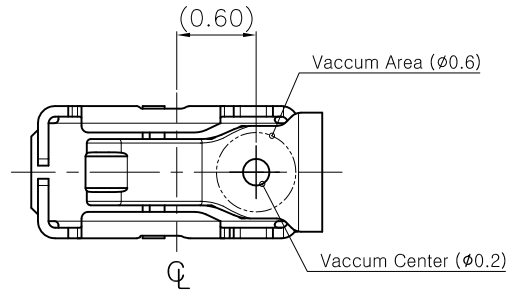
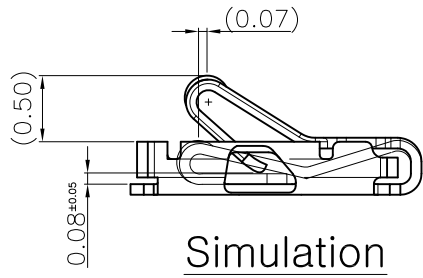


*NOTE

1. PLATING
 - Contact Area : Au 0.05 μ m Min over Pd-Ni 0.2 μ m Min. over Ni 1.5~4.0 μ m.
 - SMD Area : Au 0.05 μ m Min over Ni 1.5~4.0 μ m.
 - Bending (Other) : Ni 1.5~3.5 μ m.
2. ☆ : C.T.Q
3. ☆ : 평탄도 0.05 Max.
4. Contact 가동거리 : 0.5mm
권장 Contact 높이 : 가동거리의 60~90% 범위 내
(0.30~0.45mm) => (0.45~0.6mm)
5. 제품의 안정적 Contact을 위하여 Bending部 "B" 주위에 기구적인 간섭이 없을 것.



1	Contact	Ti-Cu		Note.1			t0.08	
No	Part name	Material		Finish			Remarks	
General Tolerance		Scale	N/S	Units	mm		CS-090A ANTENNA CONTACT	
Dimension	mm (°)	Date	2015.01.30					
X	± 0.2	Drawn	Design	Checked	Reviewed	Approved	Customer Drawing	
X.X	± 0.15							
X.XX	± 0.1							
X.XXX	± 0.05							
ANGLE		± 2°		Sheet		1 of 1		
		협진커넥터(주) HYUPJIN CONNECTOR Co.,Ltd.		SW No.		RI-CS-090A-A1.DWG		Rev.
								0